

To the extent the rejection of cancelled claim 1 might apply to claim 5, it is under 35 USC 103 for obviousness from APA (admitted prior art) Fig. 1a, "... because applicant has not disclosed that the dimensions [the second length being larger than the first length] are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical ...." This is incorrect.

Page 1, lines 17-23 (as numbered), explain why, with APA Fig. 1a, a testing instrument cannot detect adhesive thickness and/or overflow and why (product failure) such testing is important.

Page 3, lines 21-28, explain why, with the claimed invention, these problems are solved.

Referring to Figure 1b, because the size of the second chip 14 is larger than that of the plate 13, the testing instrument cannot detect the thickness of the adhesive layer 15 and the size of the overflow adhesive portion 16. If the adhesive layer 15 is too thin or the overflow adhesive portion 16 is too large, the adhesive on the overflow adhesive portion 16 will be broken so that the second chip 14 cannot exactly adhere to the plate 13; which will cause the semiconductor chip package product failure.


Referring to Figure 2b, the second chip 24 has two opposed longitudinal sides defining a first length L1. Corresponding to the two longitudinal sides of the second chip 24, the plate 23 has two opposed longitudinal sides defining a second length L2. The second length L2 is larger than the first length L1 to expose the opposed longitudinal sides of the plate 23. An overflow adhesive portion 26 is formed between the plate 23 and the second chip 24, and he

overflow adhesive portion 26 exposes on the plate 23. Therefore, the testing instrument can detect the size of the overflow adhesive portion 26 and the thickness of the adhesive layer 25 so as to control the quality of the stacked semiconductor chip package. The adhesive strength between the second chip 24 and the plate 23 can be augmented to raise the reliability of the stacked semiconductor chip package product.

Therefore, the Applicant believes that the unobvious purpose and the unexpected result of the invention have clearly disclosed in the specification. The citations do not teach or suggest these technical features of the invention.

Reconsideration and allowance are, therefore, requested.

Respectfully submitted,



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